

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO: MAIL STOP: OFFICE OF PUBLICATIONS, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, ON THE DATE INDICATED BELOW.

BY: Lara Jomm

DATE: July 28, 2004

**PATENT**  
**OFFICE OF PUBLICATIONS**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re:	Patent Application of	:	
	<b>Noboru Higashi <i>et al.</i></b>	:	
		:	Group Art Unit 2877
Conf. No.:	7117	:	
		:	
Appln. No.:	09/916,181	:	Allowed: March 1, 2004
Patent No.:	US 6,765,667 B2	:	Issued: July 20, 2004
		:	
Filed:	July 26, 2001	:	
		:	
For:	METHOD FOR INSPECTION OF	:	Attorney Docket No.
	CIRCUIT BOARDS AND	:	No. <b>8861-413US</b>
	APPARATUS FOR INPECTION OF	:	<b>(P26315-01)</b>
	CIRCUIT BOARDS	:	

**TRANSMITTAL LETTER**

Although it is Applicants' opinion that the claims filed by way of amendment are substantially embraced in the statement of invention or in the claims originally filed, Applicant's herewith file a Supplemental Declaration for precautionary purposes under 37 CFR 1.67.

Respectfully submitted,

**NOBORU HIGASHI *ET AL.***

7/28/04  
Date

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LS/TMF  
Enclosure

**SUPPLEMENTAL DECLARATION**  
(Original Application)

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed, as amended by any and all amendments entered during the prosecution of the patent application identified herein, and for which a patent is sought on the invention entitled **METHOD FOR INSPECTION OF CIRCUIT BOARDS AND APPARATUS FOR INSPECTION OF CIRCUIT BOARDS** the specification of which was filed on **July 26, 2001** as Application No. **09/916,181**.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any and all amendments entered during the prosecution of the application.

I acknowledge the duty to disclose information which is material to patentability in accordance with Title 37, Code of Federal Regulations, Section 1.56.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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